

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.23643	100.0	3.4
			Subtotal	0.23643	100	3.4
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01843	100.0	0.26507
	Pure metal	Aluminium (Al)	7429-90-5	0.16689	100.0	2.4
			Subtotal	0.18532	200	2.66507
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.73845	100.0	25
			Subtotal	1.73845	100	25
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02336	0.04	0.336
	Copper alloy	Iron (Fe)	7439-89-6	0.05841	0.1	0.84
	Copper alloy	Copper (Cu)	7440-50-8	58.33004	99.86	838.824
			Subtotal	58.41181	100	840
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.40301	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.25841	16.0	90
	Filler	Silica fused	60676-86-0	29.33629	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.11735	0.3	1.6875
			Subtotal	39.11506	100	562.5
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01565	5.0	0.225
	Lead alloy	Silver (Ag)	7440-22-4	0.00782	2.5	0.1125
	Lead alloy	Lead (Pb)	7439-92-1	0.28945	92.5	4.1625
			Subtotal	0.31292	100	4.5
			Total	99.99999	100	1438.06507

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